

TC4421/TC4422

9A High-Speed MOSFET Drivers

Features

- · High Peak Output Current: 9A
- · Wide Input Supply Voltage Operating Range:
 - 4.5V to 18V
- · High Continuous Output Current: 2A Max
- · Fast Rise and Fall Times:
 - 30 nsec with 4,700 pF Load
 - 180 nsec with 47,000 pF Load
- · Short Propagation Delays: 30 nsec (typ)
- · Low Supply Current:
 - With Logic '1' Input -- 200 μA (typ)
 - With Logic '0' Input -- 55 μA (typ)
- Low Output Impedance: 1.4Ω (typ)
- Latch-Up Protected: Will Withstand 1.5A Output Reverse Current
- Input Will Withstand Negative Inputs Up To 5V
- Pin Compatible with TC4420/TC4429 6A MOSFET driver

Applications

- · Line Drivers for Extra-Heavily-Loaded Lines
- · Pulse Generators
- · Driving the Largest MOSFETs and IGBTs
- · Local Power ON/OFF Switch
- · Motor and Solenoid Driver

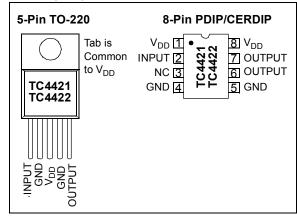
General Description

The TC4421/TC4422 are high current buffer/drivers capable of driving large MOSFETs and IGBTs.

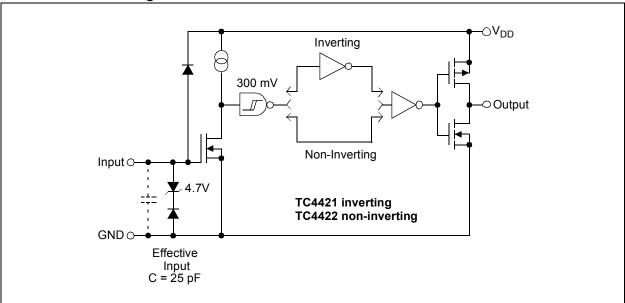
They are essentially immune to any form of upset, except direct overvoltage or over-dissipation – they cannot be latched under any conditions within their power and voltage ratings; they are not subject to damage or improper operation when up to 5V of ground bounce is present on their ground terminals; they can accept, without either damage or logic upset, more than 1A inductive current of either polarity being forced back into their outputs. In addition, all terminals are fully protected against up to 4 kV of electrostatic discharge.

The TC4421/TC4422 inputs may be driven directly from either TTL or CMOS (3V to 18V). In addition, 300 mV of hysteresis is built into the input, providing noise immunity and allowing the device to be driven from slowly rising or falling waveforms.

Package Types



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Supply Voltage	+20V
Input Voltage(V _{DD} + 0.3V) to	(GND - 5V)
Input Current (V _{IN} > V _{DD})	50 mA
Package Power Dissipation (T _A ≤ 70°C)	
PDIP	730 mW
CERDIP	800 mW
5-Pin TO-220	1.6W
Package Power Dissipation (T _A ≤ 25°C)	
5-Pin TO-220 (With Heatsink)	12.5W
Derating Factors (To Ambient)	
PDIP	8 mW/°C
CERDIP	6.4 mW/°C
5-Pin TO-220	12 mW/°C
Thermal Impedances (To Case)	
5-Pin TO-220 R _{θJ-C}	10°C/W

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.								
Parameters	Sym	Min	Тур	Max	Unit s	Conditions		
Input								
Logic '1', High Input Voltage	V_{IH}	2.4	1.8	_	V			
Logic '0', Low Input Voltage	V_{IL}	_	1.3	0.8	V			
Input Current	I _{IN}	-10	_	+10	μΑ	$0V \le V_{IN} \le V_{DD}$		
Output								
High Output Voltage	V _{OH}	V _{DD} – 0.025	_	_	V	DC TEST		
Low Output Voltage	V _{OL}	_	_	0.025	V	DC TEST		
Output Resistance, High	R _{OH}	_	1.4	_	Ω	I _{OUT} = 10 mA, V _{DD} = 18V		
Output Resistance, Low	R _{OL}	_	0.9	1.7	Ω	I _{OUT} = 10 mA, V _{DD} = 18V		
Peak Output Current	I _{PK}	_	9.0	_	Α	V _{DD} = 18V		
Continuous Output Current	I _{DC}	2	_	_	Α	10V ≤ V _{DD} ≤ 18V, T _A = +25°C (TC4421/TC4422 CAT only) (Note 2)		
Latch-Up Protection Withstand Reverse Current	I _{REV}	_	>1.5	_	Α	Duty cycle ≤ 2%, t ≤ 300 µsec		
Switching Time (Note 1)								
Rise Time	t _R	_	60	75	nsec	Figure 4-1 , C _L = 10,000 pF		
Fall Time	t _F	_	60	75	nsec	Figure 4-1 , C _L = 10,000 pF		
Delay Time	t _{D1}	_	30	60	nsec	Figure 4-1		
Delay Time	t _{D2}	_	33	60	nsec	Figure 4-1		
Power Supply				•	•			
Power Supply Current	I _S	_	0.2 55	1.5 150	mΑ μΑ	V _{IN} = 3V V _{IN} = 0V		
Operating Input Voltage	V_{DD}	4.5		18	V			

Note 1: Switching times ensured by design.

2: Tested during characterization, not production tested.

DC CHARACTERISTICS (OVER OPERATING TEMPERATURE RANGE)

Electrical Specifications: Unless otherwise noted, over operating temperature range with 4.5V \leq V _{DD} \leq 18V.									
Parameters	Sym	Min	Тур	Max	Units	Conditions			
Input									
Logic '1', High Input Voltage	V _{IH}	2.4	_	_	V				
Logic '0', Low Input Voltage	V_{IL}	_	_	0.8	V				
Input Current	I _{IN}	-10	_	+10	μA	$0V \le V_{IN} \le V_{DD}$			
Output									
High Output Voltage	V _{OH}	V _{DD} - 0.025	_	_	V	DC TEST			
Low Output Voltage	V _{OL}	_	_	0.025	V	DC TEST			
Output Resistance, High	R _{OH}	_	2.4	3.6	Ω	I _{OUT} = 10 mA, V _{DD} = 18V			
Output Resistance, Low	R _{OL}	_	1.8	2.7	Ω	I _{OUT} = 10 mA, V _{DD} = 18V			
Switching Time (Note 1)									
Rise Time	t _R	_	60	120	nsec.	Figure 4-1 , C _L = 10,000 pF			
Fall Time	t _F	_	60	120	nsec.	Figure 4-1 , C _L = 10,000 pF			
Delay Time	t _{D1}	_	50	80	nsec.	Figure 4-1			
Delay Time	t _{D2}	_	65	80	nsec.	Figure 4-1			
Power Supply									
Power Supply Current	I _S	_	_	3	mA	V _{IN} = 3V			
		_		0.2		V _{IN} = 0V			
Operating Input Voltage	V_{DD}	4.5	_	18	V				

Note 1: Switching times ensured by design.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with 4.5V \leq V _{DD} \leq 18V.								
Parameters	Sym	Min	Тур	Max	Units	Conditions		
Temperature Ranges								
Specified Temperature Range (C)	T _A	0	_	+70	°C			
Specified Temperature Range (E)	T _A	-40	_	+85	°C			
Specified Temperature Range (M)	T _A	-55	_	+125	°C			
Specified Temperature Range (V)	T _A	-40	_	+125	°C			
Maximum Junction Temperature	TJ	_	_	+150	°C			
Storage Temperature Range	T _A	-65	_	+150	°C			
Package Thermal Resistances								
Thermal Resistance, 8L-PDIP	θ_{JA}	_	125	_	°C/W			
Thermal Resistance, 8L-CERDIP	θ_{JA}	_	150	_	°C/W			
Thermal Resistance, 5L-TO-220	θ_{JA}	_	71	_	°C/W			

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.

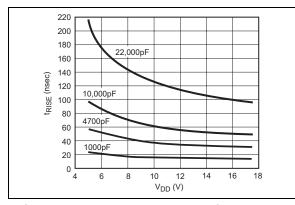
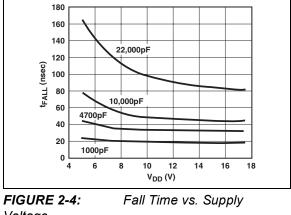


FIGURE 2-1: Rise Time vs. Supply Voltage.



Voltage.

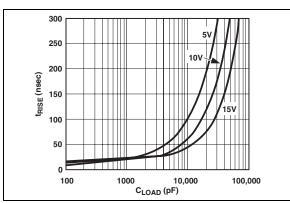


FIGURE 2-2: Rise Time vs. Capacitive Load.

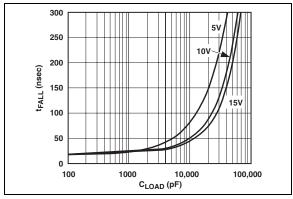


FIGURE 2-5: Fall Time vs. Capacitive Load.

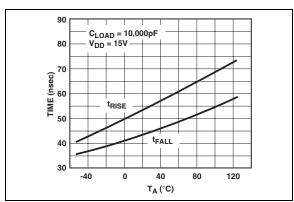


FIGURE 2-3: Rise and Fall Times vs. Temperature.

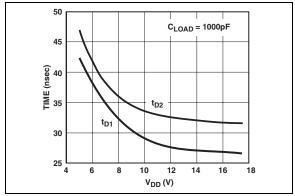


FIGURE 2-6: Propagation Delay vs. Supply Voltage.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.

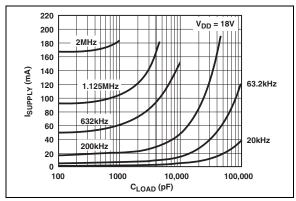


FIGURE 2-7: Supply Current vs. Capacitive Load ($V_{DD} = 18V$).

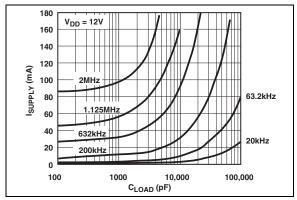


FIGURE 2-8: Supply Current vs. Capacitive Load ($V_{DD} = 12V$).

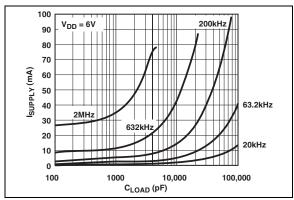


FIGURE 2-9: Supply Current vs. Capactive Load $(V_{DD} = 6V)$.

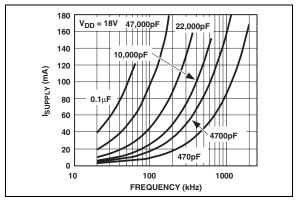


FIGURE 2-10: Supply Current vs. Frequency $(V_{DD} = 18V)$.

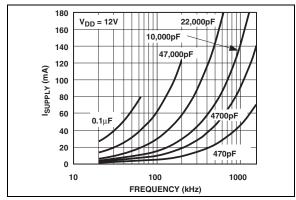


FIGURE 2-11: Supply Current vs. Frequency $(V_{DD} = 12V)$.

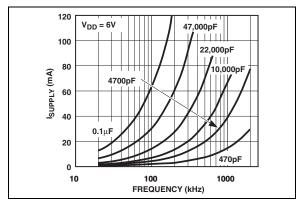


FIGURE 2-12: Supply Current vs. Frequency $(V_{DD} = 6V)$.

Note: Unless otherwise indicated, $T_A = +25^{\circ}C$ with $4.5V \le V_{DD} \le 18V$.

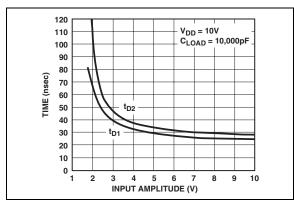


FIGURE 2-13: Propagation Delay vs. Input Amplitude.

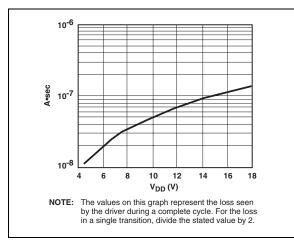


FIGURE 2-14: Crossover Energy vs. Supply Voltage.

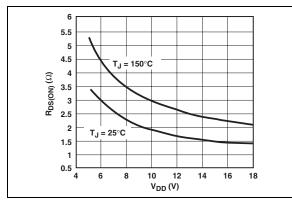


FIGURE 2-15: High-State Output Resistance vs. Supply Voltage.

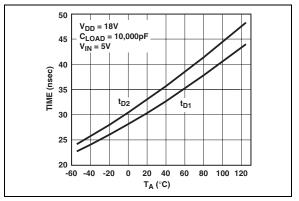


FIGURE 2-16: Propagation Delay vs. Temperature.

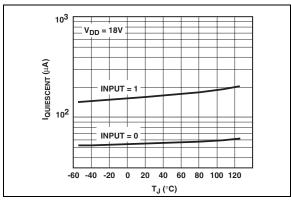


FIGURE 2-17: Quiescent Supply Current vs. Temperature.

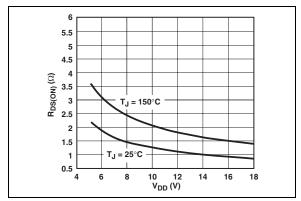


FIGURE 2-18: Low-State Output Resistance vs. Supply Voltage.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin No. (8-Pin PDIP, CERDIP)	Pin No. (5-Pin TO-220)	Symbol	Description
1	_	V_{DD}	Supply input, 4.5V to 18V
2	1	INPUT	Control input, TTL/CMOS compatible input
3	_	NC	No connection
4	2	GND	Ground
5	4	GND	Ground
6	5	OUTPUT	CMOS push-pull output
7	_	OUTPUT	CMOS push-pull output
8	3	V_{DD}	Supply input, 4.5V to 18V

3.1 Supply Input (V_{DD})

The V_{DD} input is the bias supply for the MOSFET driver and is rated for 4.5V to 18V with respect to the ground pin. The V_{DD} input should be bypassed to ground with a local ceramic capacitor. The value of the capacitor should be chosen based on the capacitive load that is being driven. A minimum value of 1.0 μ F is suggested.

3.2 Control Input

The MOSFET driver input is a high-impedance, TTL/CMOS-compatible input. The input also has 300 mV of hysteresis between the high and low thresholds that prevents output glitching even when the rise and fall time of the input signal is very slow.

3.3 CMOS Push-Pull Output

The MOSFET driver output is a low-impedance, CMOS, push-pull style output, capable of driving a capacitive load with 9.0A peak currents. The MOSFET driver output is capable of withstanding 1.5A peak reverse currents of either polarity.

3.4 Ground

The ground pins are the return path for the bias current and for the high peak currents that discharge the load capacitor. The ground pins should be tied into a ground plane or have very short traces to the bias supply source return.

4.0 APPLICATIONS INFORMATION

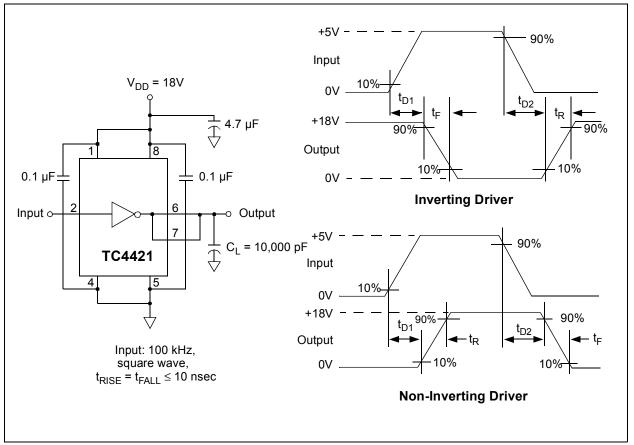


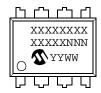
FIGURE 4-1: Switching Time Test Circuits.

5.0 PACKAGING INFORMATION

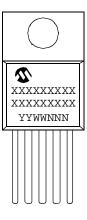
5.1 Package Marking Information



8-Lead CERDIP (300 mil)



5-Lead TO-220



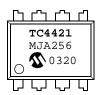
Example:

TC4421

CPA256

\$\infty\$ 0320

Example:



Example:



Legend: XX...X Customer specific information*

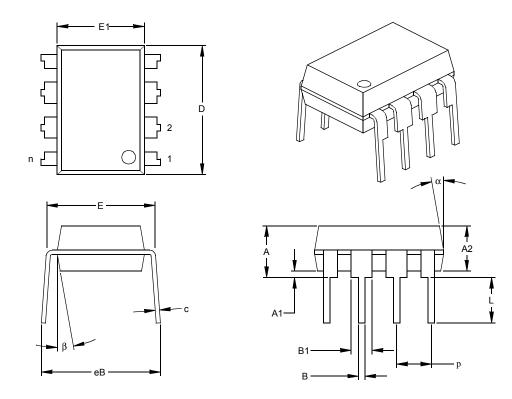
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

* Standard OTP marking consists of Microchip part number, year code, week code, and traceability code.

8-Lead Plastic Dual In-line (P) - 300 mil (PDIP)



	Units		INCHES*		N	IILLIMETERS	3
Dimensi	on Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

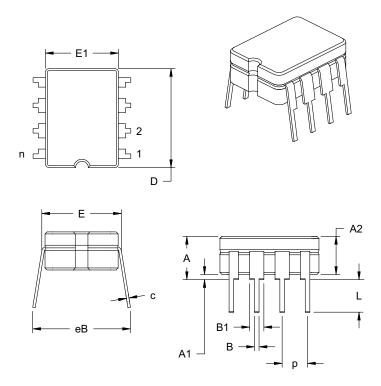
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

.010" (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-018

^{*} Controlling Parameter § Significant Characteristic

8-Lead Ceramic Dual In-line - 300 mil (CERDIP)

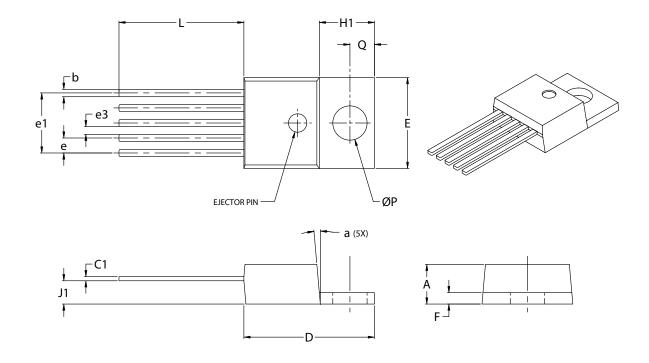


		INCHES*		MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.160	.180	.200	4.06	4.57	5.08
Standoff §	A1	.020	.030	.040	0.51	0.77	1.02
Shoulder to Shoulder Width	E	.290	.305	.320	7.37	7.75	8.13
Ceramic Pkg. Width	E1	.230	.265	.300	5.84	6.73	7.62
Overall Length	D	.370	.385	.400	9.40	9.78	10.16
Tip to Seating Plane	L	.125	.163	.200	3.18	4.13	5.08
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.055	.065	1.14	1.40	1.65
Lower Lead Width	В	.016	.018	.020	0.41	0.46	0.51
Overall Row Spacing	eВ	.320	.360	.400	8.13	9.15	10.16

*Controlling Parameter
JEDEC Equivalent: MS-030

Drawing No. C04-010

5-Lead TO-220



	Units		ES*	MILLIMETERS		
Dimension Limi	Dimension Limits		MAX	MIN	MAX	
Lead Pitch	e	.060	.072	1.52	1.83	
Overall Lead Centers	e1	.263	.273	6.68	6.93	
Space Between Leads	e3	.030	.040	0.76	1.02	
Overall Height	Α	.160	.190	4.06	4.83	
Overall Width	E	.385	.415	9.78	10.54	
Overall Length	D	.560	.590	14.22	14.99	
Flag Length	H1	.234	.258	5.94	6.55	
Flag Thickness	F	.045	.055	1.14	1.40	
Through Hole Center	Q	.103	.113	2.62	2.87	
Through Hole Diameter	Р	.146	.156	3.71	3.96	
Lead Length	L	.540	.560	13.72	14.22	
Base to Bottom of Lead	J1	.090	.115	2.29	2.92	
Lead Thickness	C1	.014	.022	0.36	0.56	
Lead Width	b	.025	.040	0.64	1.02	
Mold Draft Angle	a	3°	7°	3°	7°	

^{*}Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC equivalent: TO-220

Drawing No. C04-036

TC4421/TC4422

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>X</u> / <u>XX</u>	Examples:
Device	Temperature Package Range	a) TC4421CAT: 9A High-Speed Inverting MOSFET driver, TO-220 package, 0°C to +70°C.
Device: Temperature Range:	TC4421: 9A High-Speed MOSFET Driver, Inverting TC4422: 9A High-Speed MOSFET Driver, Non-Inverting C = 0°C to +70°C	b) TC4421MJA: 9A High-Speed Inverting MOSFET Driver, CERDIP package, -55°C to +125°C.
	E = -40°C to +85°C V = -40°C to +125°C M = -55°C to +125°C (CERDIP Only)	a) TC4422VPA: 9A High-Speed Non-Inverting MOSFET driver, PDIP package,
Package:	AT = TO-220, 5-lead JA = Ceramic Dual In-line (300 mil Body), 8-lead PA = Plastic DIP (300 mil Body), 8-lead	b) TC4422EPA: 9A High-Speed Non-Inverting MOSFET driver, PDIP package, -40°C to +85°C.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- 1. Your local Microchip sales office
- The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
- 3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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TC4421/TC4422

NOTES:

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